

SCANNED TO 4 Q.A.

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	APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER	
•	09/802443	D	257 438	61.2	281770	Yeusikou ·	€.
	Rajendra Marcos Ka Walter Bu	rnezos			2825		

Flip chip-in-leadframe package and process

PTO-2040 12/99

RATENT NUMBER

PREPARED AND APPROVED FOR ISSUE

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TERMINAL	QRAWINGS /			CLAIMS ALLOWED		
L- DISCLAIMER	Sheets Drwg.	Aigs. Drwg.	Print Fig.	Total Claims $\mathcal{Z}\mathcal{D}$	Print Claim for O.G.	
a) The term of this patent subsequent to(date) has been disclaimed.	(Axelstant E	xaminer)	(Date)	NOTICE OF AL	LOWANCE MAILED	
b) The term of this patent shall						
not extend beyond the expiration date of U.S Patent. No				ISS	UE FEE	
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Form PTO-438A (Rev. 10/97)

(LABEL AREA)